

Title (en)
FUSE LINK

Title (de)
SICHERUNGSEINSATZ

Title (fr)
Liaison Fusible

Publication
EP 1285463 A2 20030226 (EN)

Application
EP 01937502 A 20010518

Priority
• US 0115998 W 20010518
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Abstract (en)
[origin: WO0193331A2] Described herein is a fuse incorporating a covering layer disposed on a conductive layer, which is disposed on a polysilicon layer. The covering layer preferably comprises a relatively inert material, such as a nitride etchant barrier. The covering layer preferably has a region of relatively less-inert filler material. Upon programming of the fuse, the conductive layer, which can be a silicide, preferentially degrades in the region underlying the filler material of the covering layer. This preferential degradation results in a predictable "blowing" of the fuse in the fuse region underlying the filler material. Since the "blow" area is predictable, damage to adjacent structures can be minimized or eliminated.

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H01L 23/525

IPC 8 full level
H01L 21/82 (2006.01); **H01L 23/525** (2006.01)

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Citation (search report)
See references of WO 0193331A2

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